Supplier Name: Contact Info:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	05/31/2022

Details for "LM3263TME/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM3263TME/NOPB	SNAGCU	Level-1-260C-UNLIM	Texas Instruments Electronics	YFQ 16	2.059x2.059x.35	4.7

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Back Side Coating	*		· · · · · ·				-
Other Inorganic Materials	Fused Silica	60676-86-0	0.238394	78.099999	781000	5.046308	50463
Other Plastics and Rubber	Carbon Black	1333-86-4	0.002442	0.800021	8000	0.051692	517
Other Plastics and Rubber	Other Filler		0.005494	1.799883	17999	0.116297	1163
Thermoplastics	Epoxy	85954-11-6	0.058912	19.300096	193001	1.247045	12470
Sub-Total			0.305242	100	1000000	6.461342	64613
Semiconductor Device	*						-
Ceramics / Glass	Doped Silicon	7440-21-3	3.455813	100	1000000	73.152415	731524
Sub-Total			3.455813	100	1000000	73.152415	731524
Solder Bump	*						-
Copper and Its Alloys	Copper	7440-50-8	0.004815	0.499963	5000	0.101924	1019
Nickel and Its Alloys	Nickel	7440-02-0	0.000482	0.050048	500	0.010203	102
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.946218	98.249975	982500	20.029478	200295
Precious Metals	Silver	7440-22-4	0.011557	1.200014	12000	0.244638	2446
Sub-Total			0.963072	100	1000000	20.386243	203862
-							
Total	1		4.724127			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

To put advantage of the substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/31/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures. TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.